

Description

The HXY60N03D uses advanced trench technology

to provide excellent R_{DS(ON)}, low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

D S G

TO252-2L

General Features

 $V_{DS} = 30V I_{D} = 60 A$

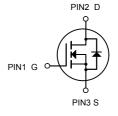
 $R_{DS(ON)} < 9m\Omega @ V_{GS}=10V$

Application

Battery protection

Load switch

Uninterruptible power supply



N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
HXY60N03D	TO252-2L	60N03D XXX YYYY	2500

Absolute Maximum Ratings (TC=25°C unless otherwise specified)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	30	V
Vgs	Gate-Source Voltage	Gate-Source Voltage ±20	
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	60	А
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	40	А
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	13.6	А
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	11.4	А
Ірм	Pulsed Drain Current ²	110	А
EAS	Single Pulse Avalanche Energy ³	57.8	mJ
las	Avalanche Current	34	А
P _D @T _C =25°C	Total Power Dissipation ⁴	41	W
P _D @T _A =25°C	Total Power Dissipation ⁴ 2.42		W
Тѕтс	Storage Temperature Range	Storage Temperature Range -55 to 175	
TJ	Operating Junction Temperature Range	Operating Junction Temperature Range -55 to 175	
RøJA	Thermal Resistance Junction-ambient (Steady State) ¹	Resistance Junction-ambient (Steady State) ¹ 62	
R _θ JC	Thermal Resistance Junction-Case ¹	3.6	°C/W



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BVpss	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	30			V	
△BVbss/△TJ	BVDSS Temperature Coefficient	Reference to 25°C , I _D =1mA		0.027		V/°C	
		V _{GS} =10V , I _D =30A		7	9		
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =4.5V , I _D =15A		11	14	mΩ	
V _{GS(th)}	Gate Threshold Voltage	\\ _\\ _250\	1.2	1.5	2.5	V	
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=250uA$		-5.8		mV/°C	
IDSS	Danier Course Louis and Course	V_{DS} =24V , V_{GS} =0V , T_J =25 $^{\circ}$ C			1		
IDSS	Drain-Source Leakage Current	V _{DS} =24V , V _{GS} =0V , T _J =55°C	24V , V _{GS} =0V , T _J =55°C		5	- uA	
Igss	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA	
gfs	Forward Transconductance	V _{DS} =5V , I _D =30A		38		S	
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		2.2	3.5		
Qg	Total Gate Charge (4.5V)			12.6	17.6		
Qgs	Gate-Source Charge	V _{DS} =15V , V _{GS} =4.5V , I _D =15A		4.2	5.9	nC	
Q _{gd}	Gate-Drain Charge			5.1	7.1		
Td(on)	Turn-On Delay Time			4.6	9.2		
Tr	Rise Time	V _{DD} =15V , V _{GS} =10V , R _G =3.3		12.2	22		
Td(off)	Turn-Off Delay Time	I _D =15A		26.6	53	ns	
Tf	Fall Time			8	16		
Ciss	Input Capacitance			1317	1843		
Coss	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		163	228	pF	
Crss	Reverse Transfer Capacitance			131	183		
Is	Continuous Source Current ^{1,5}				55	Α	
Іѕм	Pulsed Source Current ^{2,5}	$V_G=V_D=0V$, Force Current			110	Α	
VsD	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C			1.2	V	
t _{rr}	Reverse Recovery Time			9.2		nS	
Qrr	Reverse Recovery Charge			2		nC	

Note:

- 1 .The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%
- 3. The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V,L=0.1mH, I_{AS} =34A
- 4.The power dissipation is limited by 175°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

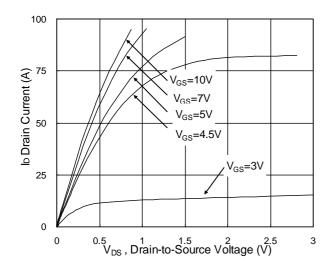


Fig.1 Typical Output Characteristics

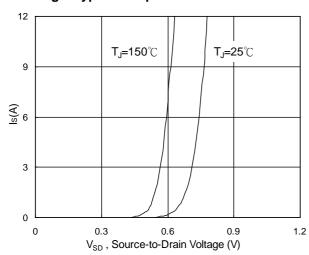


Fig.3 Forward Characteristics of Reverse

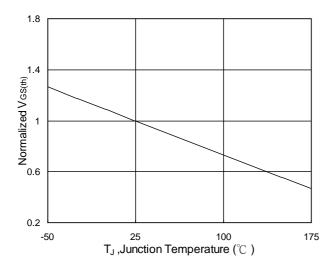


Fig.5 Normalized V_{GS(th)} vs. T_J

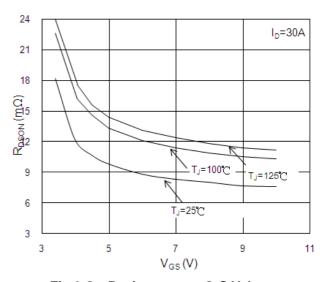


Fig.2 On-Resistance vs. G-S Voltage

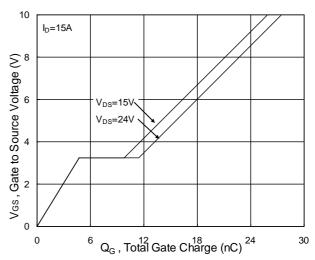


Fig.4 Gate-Charge Characteristics

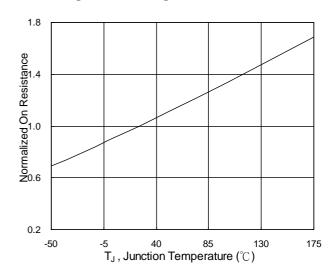
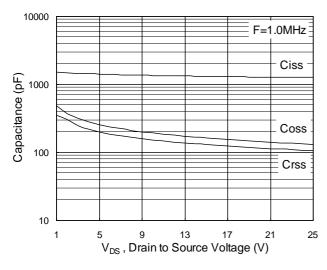


Fig.6 Normalized R_{DSON} vs. T_J



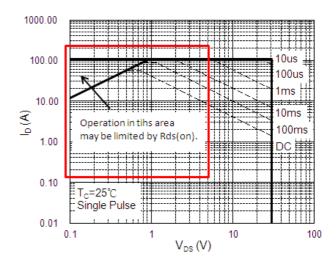


Fig.7 Capacitance

Fig.8 Safe Operating Area

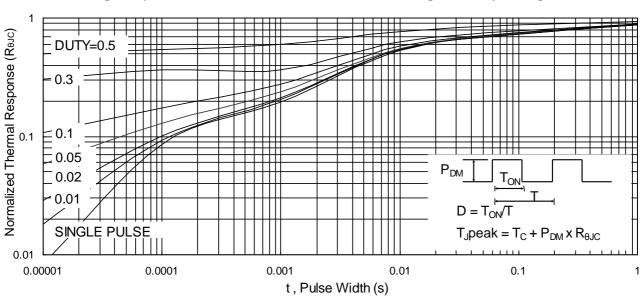
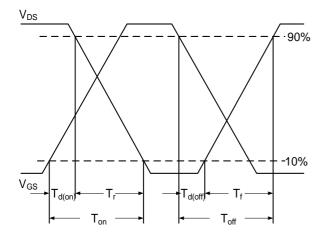
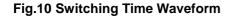


Fig.9 Normalized Maximum Transient Thermal Impedance





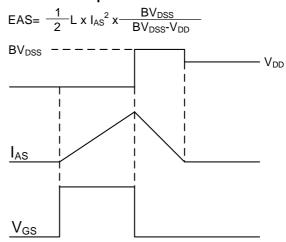
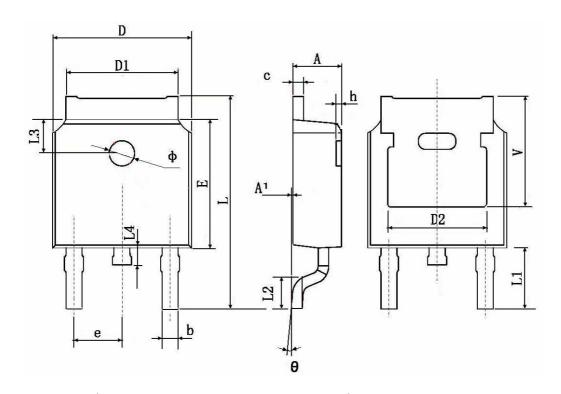


Fig.11 Unclamped Inductive Switching Waveform



TO252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
Е	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 TYP.		0.211 TYP.		



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